



Title of Change:	Addition of ON Semiconductor Gresham, Oregon, as wafer fab location (I3T50 technology), currently manufactured in Fab2, Oudenaarde, Belgium for the NCV7728DPR2G product. In addition, wire size will be increased from 1.0mil to 1.3mil.																		
Proposed Changed Material First Ship Date:	5 July 2019																		
Product Category:	Active components – Integrated circuits																		
Contact information:	Contact your local ON Semiconductor Sales Office or < Alicia.Tuckett@onsemi.com >																		
Samples:	Contact your local ON Semiconductor Sales Office to place sample order or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 45 days after publication of this change notification.																		
Sample Availability Date:	27 July 2018																		
PPAP Availability Date:	27 July 2018																		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Peter.Turlo@onsemi.com >																		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .																		
Change Category:	Type of Change																		
Process – Wafer Production	New wafer diameter																		
Process – Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor (qualification of an additional manufacturing site)																		
Process – Assembly	Change of wire size																		
Process – Assembly	Change of product marking																		
Description and Purpose: Addition of ON Semiconductor Gresham, Oregon as wafer fab location (I3T technology, 200 mm fab), currently manufactured in Fab2, Oudenaarde, Belgium (150 mm fab) to be dual sourced for the NCV7728DPR2G product. This will increase ON Semiconductor's wafer fab capacity and flexibility for this device. In addition, wire size will be increased from 1.0mil to 1.3mil.																			
<table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Qualification of an additional manufacturing site</td> <td>Fab2, Oudenaarde, Belgium</td> <td>Fab2, Oudenaarde, Belgium and Gresham, Oregon</td> </tr> <tr> <td>Wafer Diameter</td> <td>150mm</td> <td>150mm and 200mm</td> </tr> <tr> <td>Wire Size</td> <td>1.0 mil</td> <td>1.3 mil</td> </tr> </tbody> </table> <table border="1"> <thead> <tr> <th></th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Product marking change</td> <td>NCV7728</td> <td>NCV7728A</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Qualification of an additional manufacturing site	Fab2, Oudenaarde, Belgium	Fab2, Oudenaarde, Belgium and Gresham, Oregon	Wafer Diameter	150mm	150mm and 200mm	Wire Size	1.0 mil	1.3 mil		From	To	Product marking change	NCV7728	NCV7728A
	Before Change Description	After Change Description																	
Qualification of an additional manufacturing site	Fab2, Oudenaarde, Belgium	Fab2, Oudenaarde, Belgium and Gresham, Oregon																	
Wafer Diameter	150mm	150mm and 200mm																	
Wire Size	1.0 mil	1.3 mil																	
	From	To																	
Product marking change	NCV7728	NCV7728A																	



Reason / Motivation for Change:	Benefit of the change: Provide additional wafer fab capacity and flexibility for manufacturing. Risk for Late Release: Possible supply disruptions.	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.	
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines ON Gresham, Oregon	External Foundry/Subcon Sites: None
Marking of Parts/ Traceability of Change:	Line one package marking will change to NCV7728A	

Reliability Data Summary:

DEVICE NAME: NCV7728DPR2G
PACKAGE: 24 Lead SSOP .65p
RMS: 47172, 47940

Test	Specification	Condition	Results
HTOL	JESD22-A108	High Temperature Operational Life: (Test @ R/H) Tj=150°C for 1008hrs.	0 / 240 Pass
HTSL	JESD22-A103	High Temperature Storage Life (Test @ R/H) Ta=175°C for 1000hrs.	0 / 80 Pass
TC	JESD22-A104	Temperature Cycle: (Test @ R/H) -65°C to +150°C; for 1000cyc	0 / 240 Pass
HAST	JESD22-A110	Highly Accelerated Stress Test: (Test @ R/H) 130°C/85% RH, 18.8psi, bias, 192hrs	0 / 240 Pass
uHAST	JESD22-A118	Unbiased Highly Accelerated Stress Test: (Test @ R) 130°C/85% RH, 18.8psi, 192hrs	0 / 240 Pass
PC	J-STD-020 JESD-A113	Preconditioning: (Test @ R/H) SMD only; Moisture Load and Reflow	0 / all For AC, TC, HAST (MSL= 2 @ 260°C)

NOTE: AEC-1pager and Cpk report is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Current Part Number	Dual Source Part Number	Qualification Vehicle
NCV7728DPR2G	NCV7728DPR2G	NCV7728DPR2G